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INTERNAL PULL-UP HALL EFFECT LATCH

Description

AH373 is a single-digital-output Hall-Effect latch sensor with internal pull-up resistor for high temperature operation. The device includes an on-chip Hall voltage generator for magnetic sensing, an amplifier to amplify Hall voltage, and a comparator to provide switching hysteresis for noise rejection, and an output driver with a pull-up resistor. An internal band-gap regulator provides a temperature compensated supply voltage for internal circuits and allows a wide operating supply range.

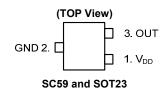
When the magnetic flux density (B) perpendicular to the package is larger than operate point (Bop), output is switched on (OUT pin is pulled low). The output state is held on until a magnetic flux density reversal falls below Brp. When B is less than Brp, the output is switched off.

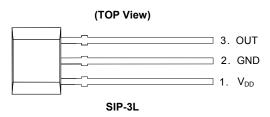
The AH373 is available in SIP-3L, SC59 and SOT23 packages.

Features

- · Bipolar Hall Effect Latch Operation
- 2.2V to 20V Operating Range
- · Single Output with Built-in Pull-up Resistor
- 25mA output Sink Capability
- -40°C to +125°C Operating Temperature
- Industry Standard SIP-3L, SC59 and SOT23 Packages
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignments





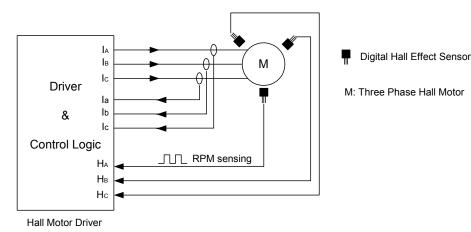
Applications

- Rotor Position Sensing for Motor Commutation
- Encoder
- Speed Measurement RPM Monitor
- Contact-less Current Switch

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Typical Application Circuits

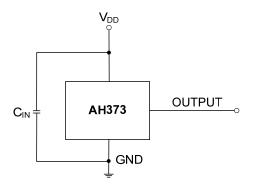


3 Phase Hall Motor





Typical Application Circuits (cont.)



Typical AH373 Circuit

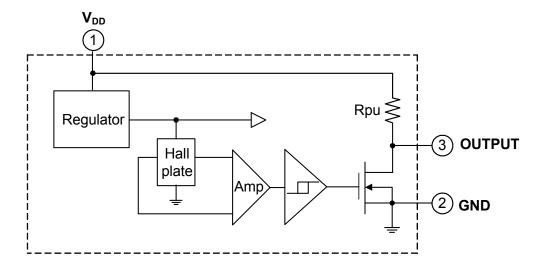
Note: 4. C_{IN} is for power stabilization and to strengthen the noise immunity, the recommended capacitance is 100nF typical

Pin Descriptions

Package: SC59, SOT23 and SIP-3L

Pin Number	Pin Name	Function
1	V_{DD}	Power Supply Input
2	GND	Ground
3	OUTPUT	Output

Functional Block Diagram







Absolute Maximum Ratings (Note 5) @TA = +25°C, unless otherwise specified.)

Symbol	Characteristics		Values	Unit
V_{DD}	Supply Voltage (Note 6)		28	V
V _{OUT} (Off)	Output "Off" Voltage		28	V
I _O (sink)	Output "On" current (sink)		25	mA
В	Magnetic Flux Density	Unlimited		
D-	Package Power Dissipation	SIP-3L	550	mW
P _D	Fackage Fower Dissipation	230	mW	
T _S	Storage Temperature Range	-65 to +150	°C	
TJ	Maximum Junction Temperature		+150	°C

Notes:

- 5. Stresses greater than the 'Absolute Maximum Ratings' specified above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.
- 6. The absolute maximum V_{DD} of 28V is a transient stress rating and is not meant as a functional operating condition. It is not recommended to operate the device at the absolute maximum rated conditions for any period of time.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Characteristic	Conditions	Rating	Unit
V_{DD}	Supply Voltage (Note 7)	Operating	2.2 to 20	V
T _A	Operating Temperature Range	Operating	-40 to +125	°C

Note: 7. The output of IC will be switched after the supply voltage is over 2.2V, but the magnetic characteristics will not be normal until the supply is over 2.5V.

Electrical Characteristics (@ T_A = +25°C, V_{DD} = 12V, unless otherwise specified.)

Symbol	Characteristic	Conditions	Min	Тур	Max	Unit
V_{OUT}	Output On Voltage	I _{OUT} = 20mA	_	300	400	mV
I _{DD}	Supply Current	B < Brp	_	2	4	mA
I _{OFF}	Output Leakage Current	Output off	_	< 0.1	10	μA
Rpu	Internal Pull-up Resistor	_	7	10	13	kΩ



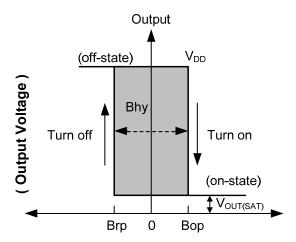


Magnetic Characteristics (Note 8) (@T_A = +25°C, V_{DD} = 2.5V to 20V, unless otherwise specified.)

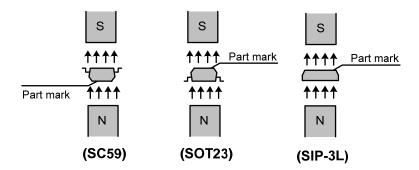
(1mT=10 Gauss)

Symbol	Characteristic	Min	Тур	Max	Unit
Bop (South pole to part marking side for SIP-3L and SOT23; North pole to part marking side for SC59)	Operation Point	5	30	60	
Brp (South pole to part marking side for SIP-3L and SOT23; North pole to part marking side for SC59)	Release Point	-60	-30	-5	Gauss
Bhy (Bopx - Brpx)	Hysteresis	_	60	_	

Note: 8. The magnetic characteristics may vary with supply voltage, operating temperature and after soldering.



(Magnetic Flux Density B)



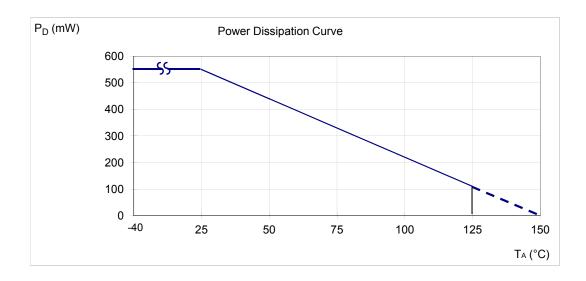




Thermal Performance Characteristics

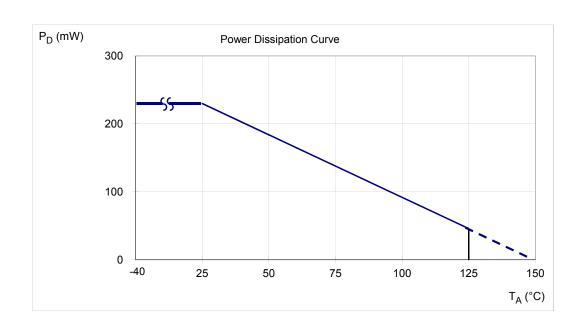
(1) Package Type: SIP-3L

T _A (°C)	25	50	60	70	80	85	90	95	100	105	110	115	120	125	130	135	140	150
P _D (mW)	550	440	396	352	308	286	264	242	220	198	176	154	132	110	88	66	44	0



(2) Package Type: SC59 and SOT23

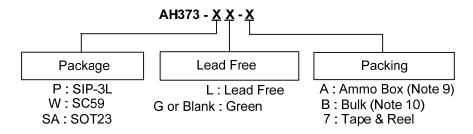
T _A (°C)	25	50	60	70	80	85	90	100	105	110	120	125	130	140	150
P _D (mW)	230	184	166	147	129	120	110	92	83	74	55	46	37	18	0







Ordering Information



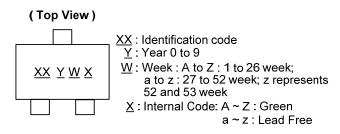
	Package		Ві	ılk	7" Tape ar	nd Reel	Ammo	Вох
Part Number	Code	(Note 11)	Quantity	Part Number Suffix	Quantity	Part Number Suffix	Quantity	Part Number Suffix
AH373-PL-A	Р	SIP-3L	NA	NA	NA	NA	4000/Box	-A
AH373-PL-B	Р	SIP-3L	1000	-B	NA	NA	NA	NA
AH373-PG-A	Р	SIP-3L	NA	NA	NA	NA	4000/Box	-A
AH373-PG-B	Р	SIP-3L	1000	-B	NA	NA	NA	NA
AH373-SA-7	SA	SOT23	NA	NA	3000/Tape & Reel	-7	NA	NA
AH373-WL-7	W	SC59	NA	NA	3000/Tape & Reel	-7	NA	NA
AH373-WG-7	W	SC59	NA	NA	3000/Tape & Reel	-7	NA	NA

Notes:

- 9. Ammo Box is for SIP-3L Spread Lead.
- 10. Bulk is for SIP-3L Straight Lead.

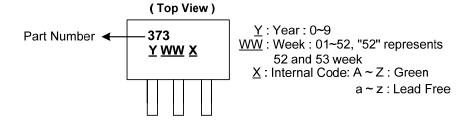
Marking Information

(1) Package Type: SC59 and SOT23



Part Number	Package	Identification Code
AH373	SC59	P2
AH373	SOT23	S2

(2) Package Type: SIP-3L



Reverse taping as shown on Diodes Inc. Surface Mount (SMD) Packaging document AP02007, which can be found on our website http://www.diodes.com/datasheets/ap02007.pdf.

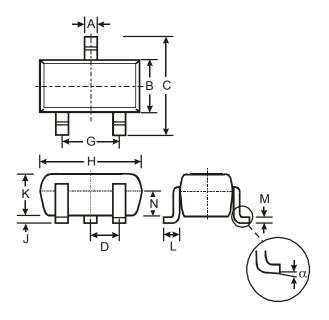




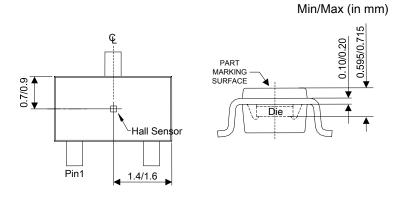
Package Outline Dimensions (All dimensions in mm.)

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(1) Package Type: SC59



	sc	59	
Dim	Min	Max	Тур
Α	0.35	0.50	0.38
В	1.50	1.70	1.60
С	2.70	3.00	2.80
D	-	-	0.95
G	1	ı	1.90
Η	2.90	3.10	3.00
7	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
М	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All [Dimensi	ions in i	mm



Sensor location

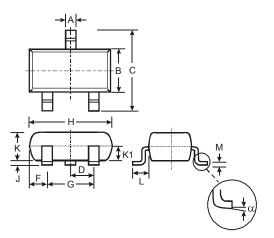




Package Outline Dimensions (cont.) (All dimensions in mm.)

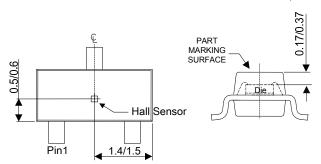
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(2) Package Type: SOT23



	SO	T23	_
Dim	Min	Max	Тур
Α	0.37	0.51	0.40
В	1.20	1.40	1.30
С	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
Н	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
М	0.085	0.18	0.11
α	0°	8°	-
All	Dimens	ions in	mm

Min/Max (in mm)



Sensor location

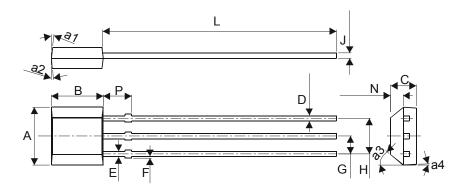




Package Outline Dimensions (cont.) (All dimensions in mm.)

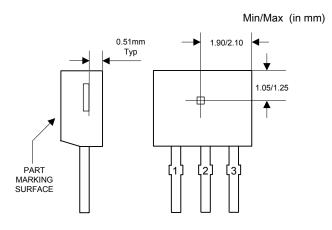
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(3) Package Type: SIP-3L for Bulk pack



Notes: 13. SIP-3L Bulk pack - Thickness J includes Burrs

SIP-	3 for Bull	k Pack
Dim	Min	Max
Α	3.9	4.3
a1	5°	Тур
a2	5°	
а3	45°	[°] Тур
a4	3°	Тур
В	2.8	3.2
С	1.40	1.60
D	0.33	0.432
Е	0.40	0.508
F	0	0.2
G	1.24	1.30
Н	2.51	2.57
J	0.35	0.43
L	14.0	15.0
N	0.63	0.84
Р	1.55	-
All Di	mension	s in mm



Sensor location

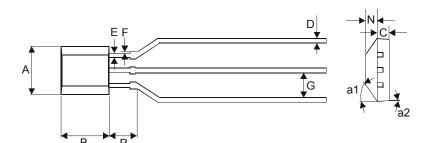




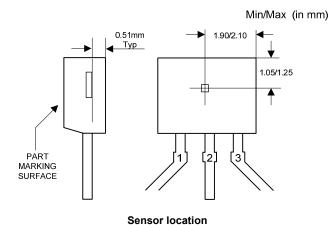
Package Outline Dimensions (cont.) (All dimensions in mm.)

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(4) Package Type: SIP-3L for Ammo pack



SIP-3 for Ammo Pack		
Dim	Min	Max
Α	3.9	4.3
a1	45° Typ	
a2	3° Typ	
В	2.8	3.2
С	1.40	1.60
D	0.35	0.41
Е	0.43	0.48
F	0	0.2
G	2.4	2.9
N	0.63	0.84
Ρ	1.55	-
All Dimensions in mm		



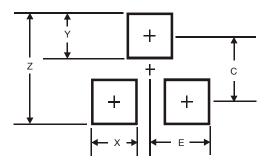




Suggested Pad Layout

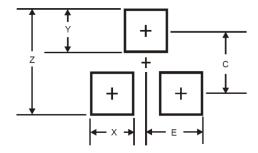
 $Please see AP02001 \ at \ http://www.diodes.com/datasheets/ap02001.pdf \ for \ the \ latest \ version.$

(1) Package Type: SC59



Dimensions	Value (in mm)
Z	3.4
Х	0.8
Y	1.0
С	2.4
E	1.35

(2) Package Type: SOT23



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
F	1.35







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